

## N-Channel Enhancement Mode MOSFET

### 1. Product Information

#### 1.1 Features

- Surface-mounted package
- Extremely low threshold voltage
- Advanced trench cell design
- ESD protected

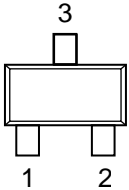
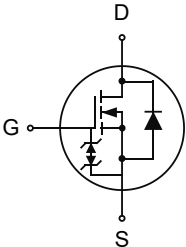
#### 1.2 Applications

- Portable appliances

#### 1.3 Quick reference

- $BV \geq 30\text{ V}$
- $P_{tot} \leq 0.27\text{ W}$
- $I_D \leq 0.8\text{ A}$
- $R_{DS(ON)} \leq 0.8\text{ m}\Omega @ V_{GS} = 4.5\text{ V}$
- $R_{DS(ON)} \leq 0.9\text{ m}\Omega @ V_{GS} = 2.5\text{ V}$
- $R_{DS(ON)} \leq 1.3\text{ m}\Omega @ V_{GS} = 1.8\text{ V}$
- $R_{DS(ON)} \leq 1.8\text{ m}\Omega @ V_{GS} = 1.5\text{ V}$
- $R_{DS(ON)} \leq 3.0\text{ m}\Omega @ V_{GS} = 1.2\text{ V}$

### 2. Pin Description

Pin	Description	Simplified Outline	Symbol
1	<b>Gate(G)</b>	 <p>Top View SOT-523</p>	
2	<b>Source(S)</b>		
3	<b>Drain(D)</b>		

## 3. Limiting Values

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>DS</sub>	Drain-Source Voltage	T <sub>A</sub> = 25 °C	30	-	V
V <sub>GS</sub>	Gate-Source Voltage	T <sub>A</sub> = 25 °C	-	±10	V
I <sub>D</sub> *	Drain Current (DC)	T <sub>A</sub> = 25 °C, V <sub>GS</sub> = 4.5 V	-	0.8	A
I <sub>DM</sub> *,**	Drain Current (Pulsed)	T <sub>A</sub> = 25 °C, V <sub>GS</sub> = 4.5 V	-	1.8	A
P <sub>tot</sub> *	Total Power Dissipation	T <sub>A</sub> = 25 °C	-	0.27	W
P <sub>tot</sub> *	Total Power Dissipation	T <sub>A</sub> = 100 °C	-	0.15	W
T <sub>stg</sub>	Storage Temperature		- 55	150	°C
T <sub>J</sub>	Junction Temperature		-	150	°C
I <sub>S</sub> *	Diode Forward Current	T <sub>A</sub> = 25 °C	-	1.8	A
R <sub>θJA</sub> *	Thermal Resistance-Junction to Ambient		-	150	°C/W

Notes:

\* Surface Mounted on 1 in<sup>2</sup> pad area, t ≤ 10 sec

\*\* Pulse width ≤ 300 μs, duty cycle ≤ 2 %

## 4. Marking Information

Product Name	Marking
KJ3001S5	<b>3001</b>

## 5. Ordering Code

Product Name	Package	Reel Size	Tape width	Quantity	Note
KJ3001S5	SOT-523	-	-	3000	

Note: KUAJIEXIN defines “ Green ” as lead-free ( RoHS compliant ) and halogen free ( Br or Cl does not exceed 900 ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500 ppm by weight; Follow IEC 61249-2-21 and IPC / JEDEC J-STD-020C )

## 6. Electrical Characteristics (T<sub>A</sub>=25°C Unless Otherwise Noted )

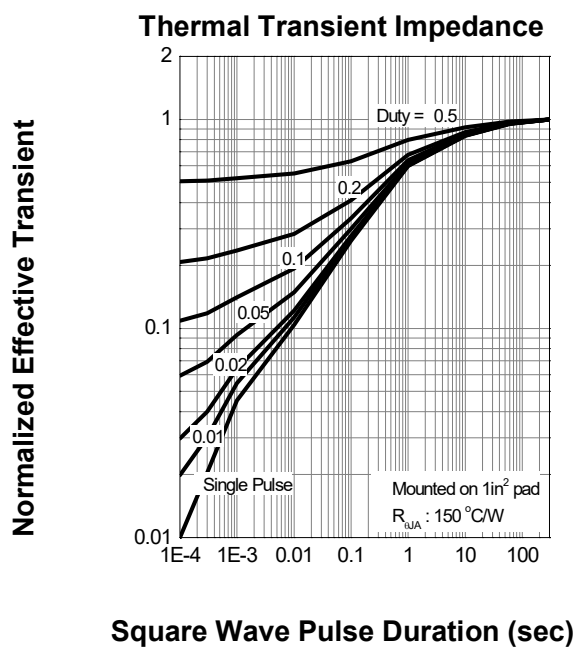
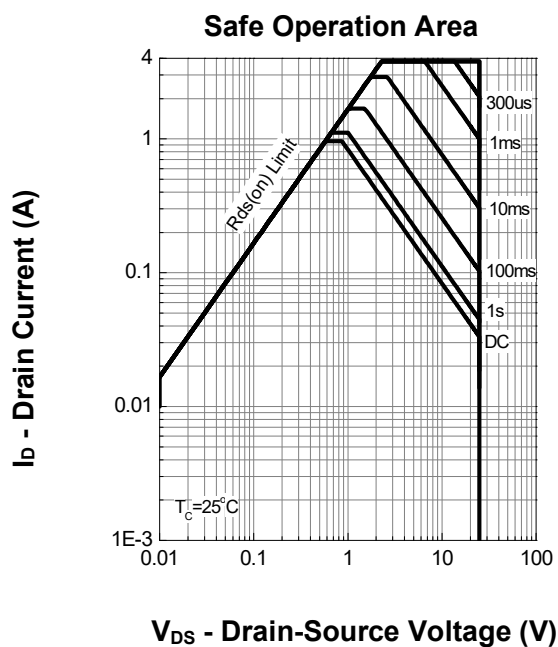
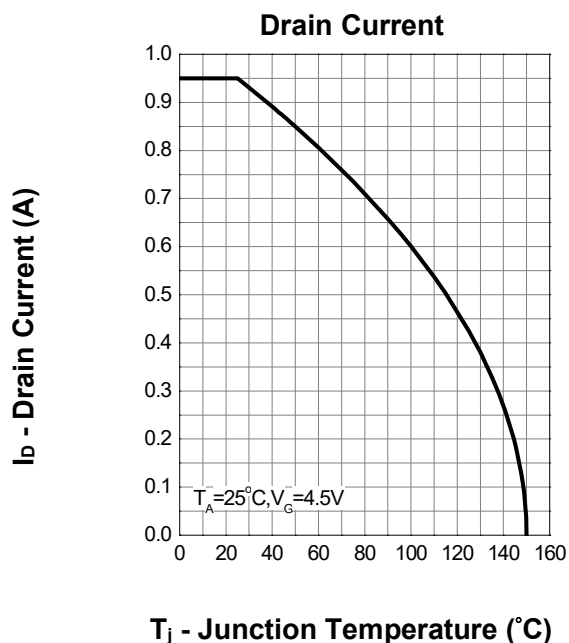
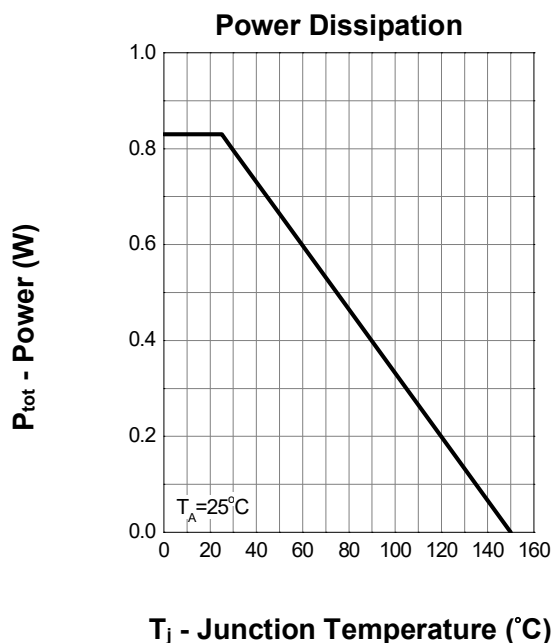
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static Characteristics</b>						
B <sub>V</sub> DSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0 V, I <sub>DS</sub> = 250 μA	30	-	-	V
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>DS</sub> = 250 μA	0.4	0.7	1.1	V
I <sub>DSS</sub>	Drain Leakage Current	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V	-	-	1	μA
		T <sub>J</sub> = 85 °C	-	-	30	μA
I <sub>GSS</sub>	Gate Leakage Current	V <sub>GS</sub> = ± 10 V, V <sub>DS</sub> = 0 V	-	-	± 10	μA
R <sub>DS(ON)</sub> <sup>a</sup>	On-State Resistance	V <sub>GS</sub> = 4.5 V, I <sub>DS</sub> = 0.5 A	-	0.7	0.8	Ω
		V <sub>GS</sub> = 2.5 V, I <sub>DS</sub> = 0.2 A	-	0.75	0.9	
		V <sub>GS</sub> = 1.8 V, I <sub>DS</sub> = 0.2 A		1.1	1.3	
		V <sub>GS</sub> = 1.5 V, I <sub>DS</sub> = 0.2 A		1.6	1.8	
		V <sub>GS</sub> = 1.2 V, I <sub>DS</sub> = 0.2 A		2.6	3.0	
<b>Diode Characteristics</b>						
V <sub>SD</sub> <sup>a</sup>	Diode Forward Voltage	I <sub>SD</sub> = 0.5 A, V <sub>GS</sub> = 0 V	-	-	1.3	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>SD</sub> = 0.5 A, dI <sub>SD</sub> / dt = 100 A / μs	-	40	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge		-	39	-	nC
<b>Dynamic Characteristics<sup>b</sup></b>						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 10 V Frequency = 1 MHz	-	30	-	pF
C <sub>oss</sub>	Output Capacitance		-	3	-	
C <sub>rss</sub>	Reverse Transfer Capacitance		-	1	-	
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DS</sub> = 30 V, V <sub>GEN</sub> = 10 V, R <sub>G</sub> = 25 Ω, R <sub>L</sub> = 60 Ω, I <sub>DS</sub> = 0.95 A	-	3.6	-	ns
t <sub>r</sub>	Turn-on Rise Time		-	3.3	-	
t <sub>d(off)</sub>	Turn-off Delay Time		-	20	-	
t <sub>f</sub>	Turn-off Fall Time		-	11	-	
<b>Charge Characteristics</b>						
Q <sub>g</sub>	Total Gate Charge	V <sub>GS</sub> = 4.5 V, V <sub>DS</sub> = 10 V, I <sub>DS</sub> = 0.95 A	-	0.6	-	pC
Q <sub>gs</sub>	Gate-Source Charge		-	0.26	-	
Q <sub>gd</sub>	Gate-Drain Charge		-	0.17	-	

Notes :

a : Pulse test ; pulse width ≤ 300 μs, duty cycle ≤ 2 %

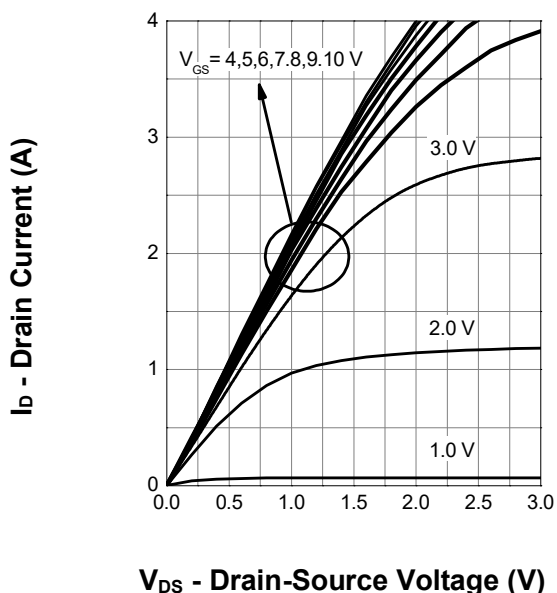
b : Guaranteed by design, not subject to production testing

## 7. Typical Characteristics

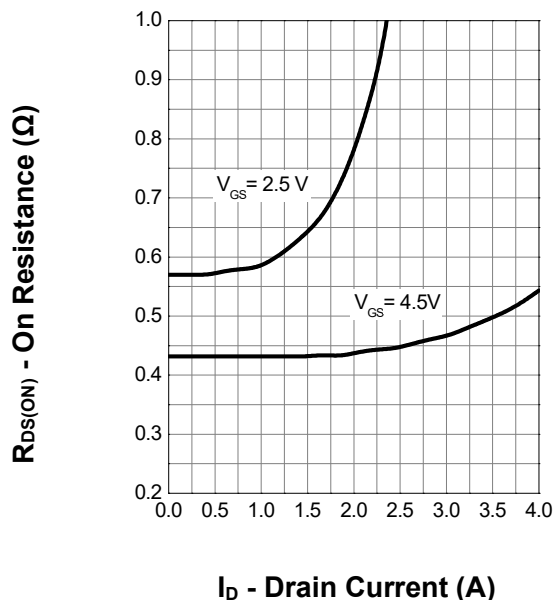


## 7. Typical Characteristics (cont.)

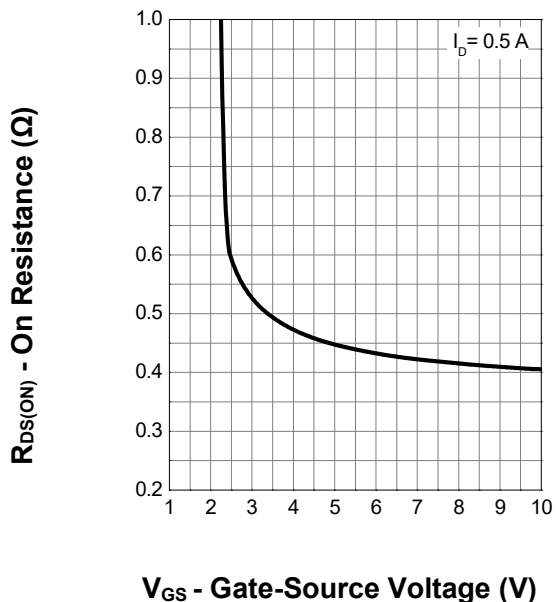
**Output Characteristics**



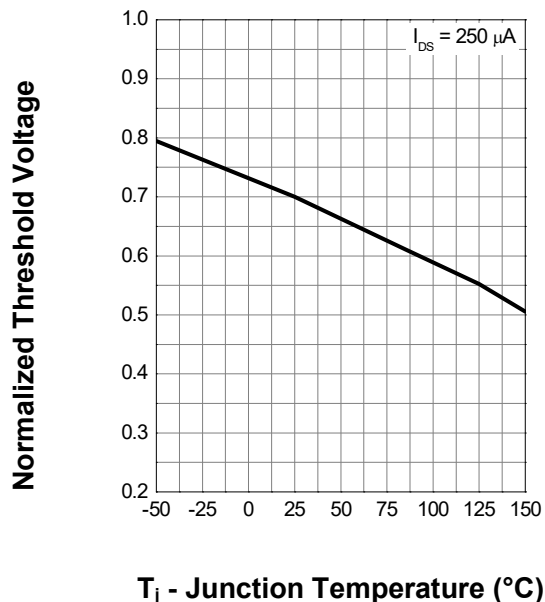
**Drain-Source On Resistance**



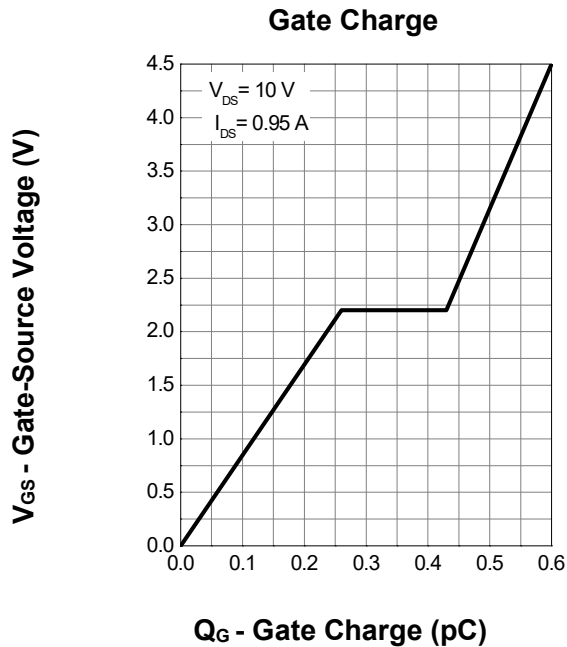
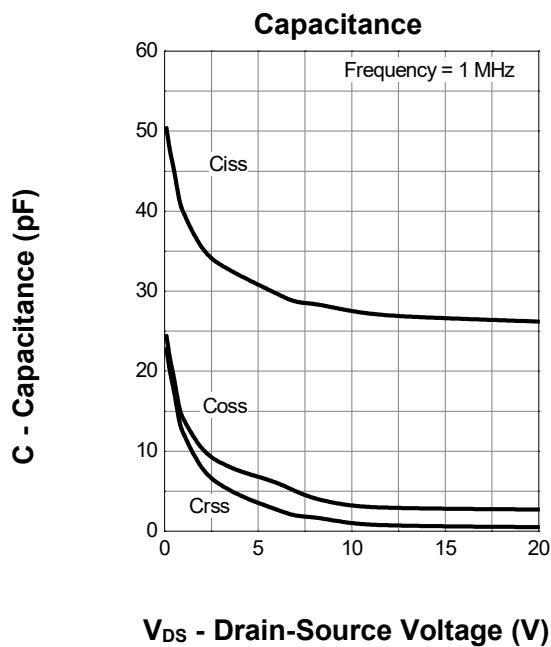
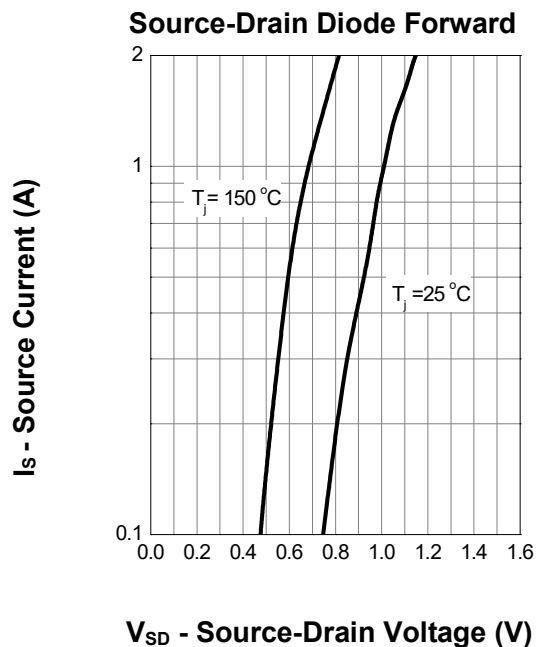
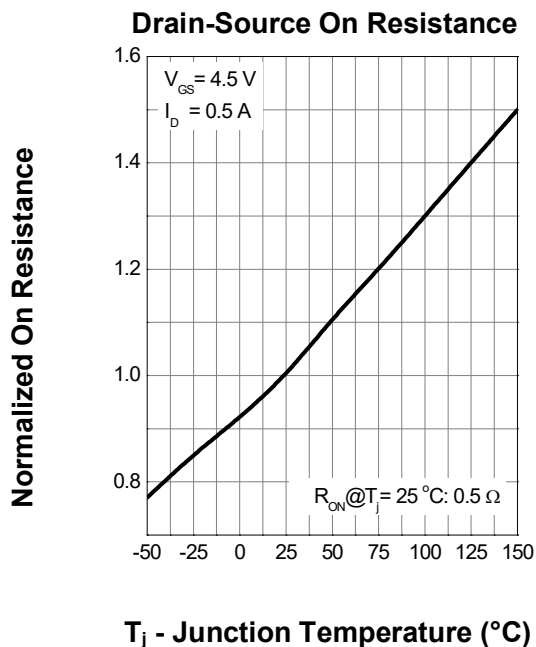
**Transfer Characteristics**



**Gate Threshold Voltage**

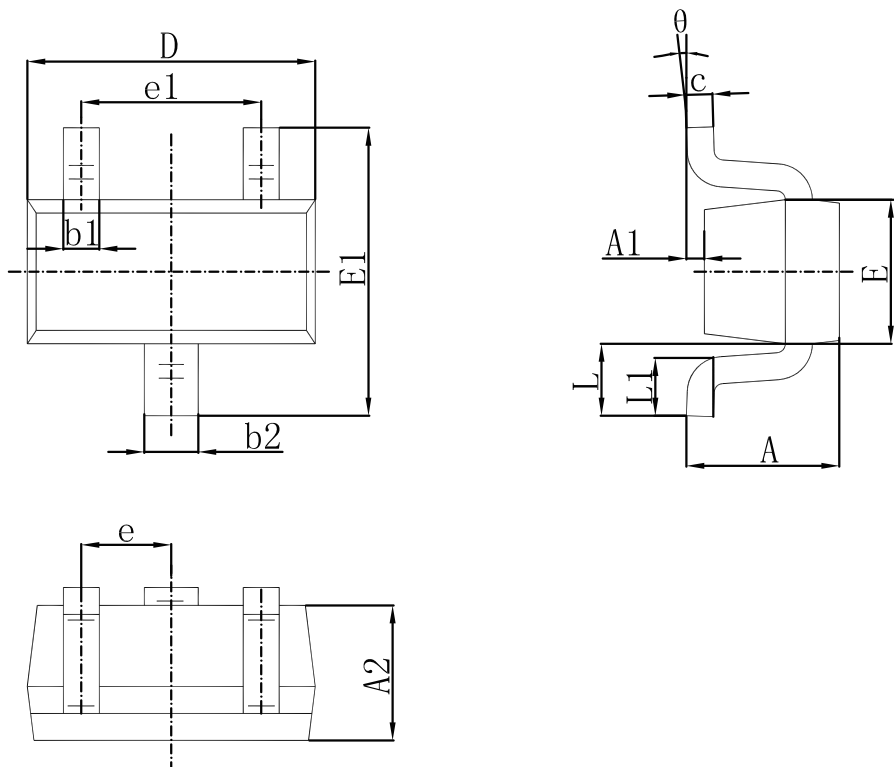


## 7. Typical Characteristics (cont.)



## 8. Package Dimensions

### SOT-523 Package



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.900	0.028	0.035
A1	0.000	0.100	0.000	0.004
A2	0.700	0.800	0.028	0.031
b1	0.150	0.250	0.006	0.010
b2	0.250	0.350	0.010	0.014
c	0.100	0.200	0.004	0.008
D	1.500	1.700	0.059	0.067
E	0.700	0.900	0.028	0.035
E1	1.450	1.750	0.057	0.069
e	0.500 TYP.		0.020 TYP.	
e1	0.900	1.100	0.035	0.043
L	0.400 REF.		0.016 REF.	
L1	0.260	0.460	0.010	0.018
$\theta$	0°	8°	0°	8°